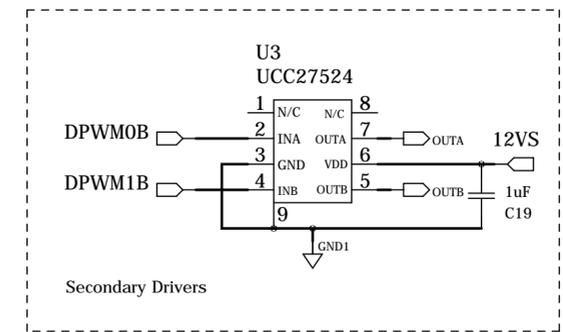
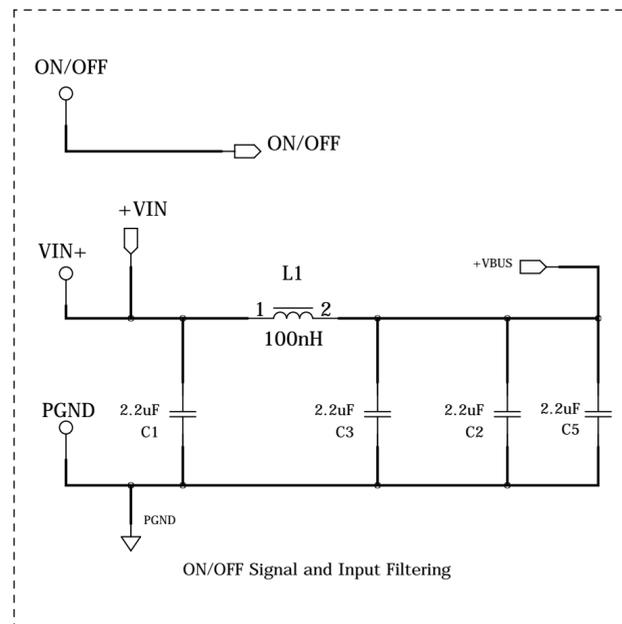
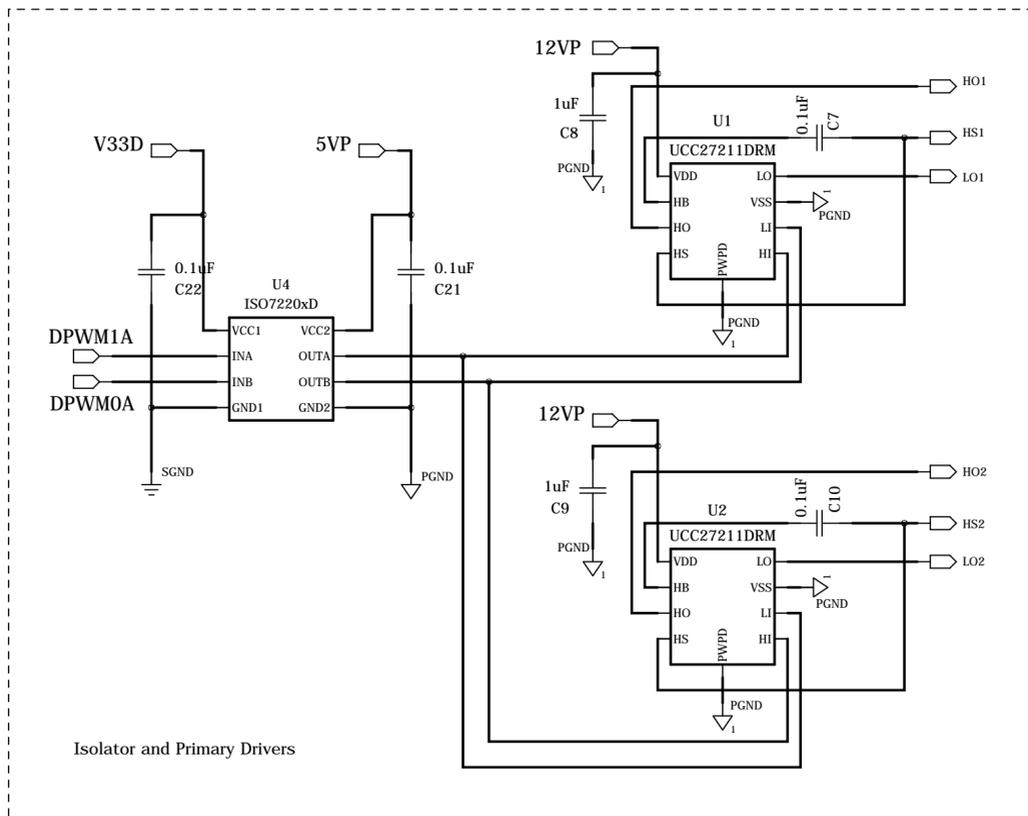
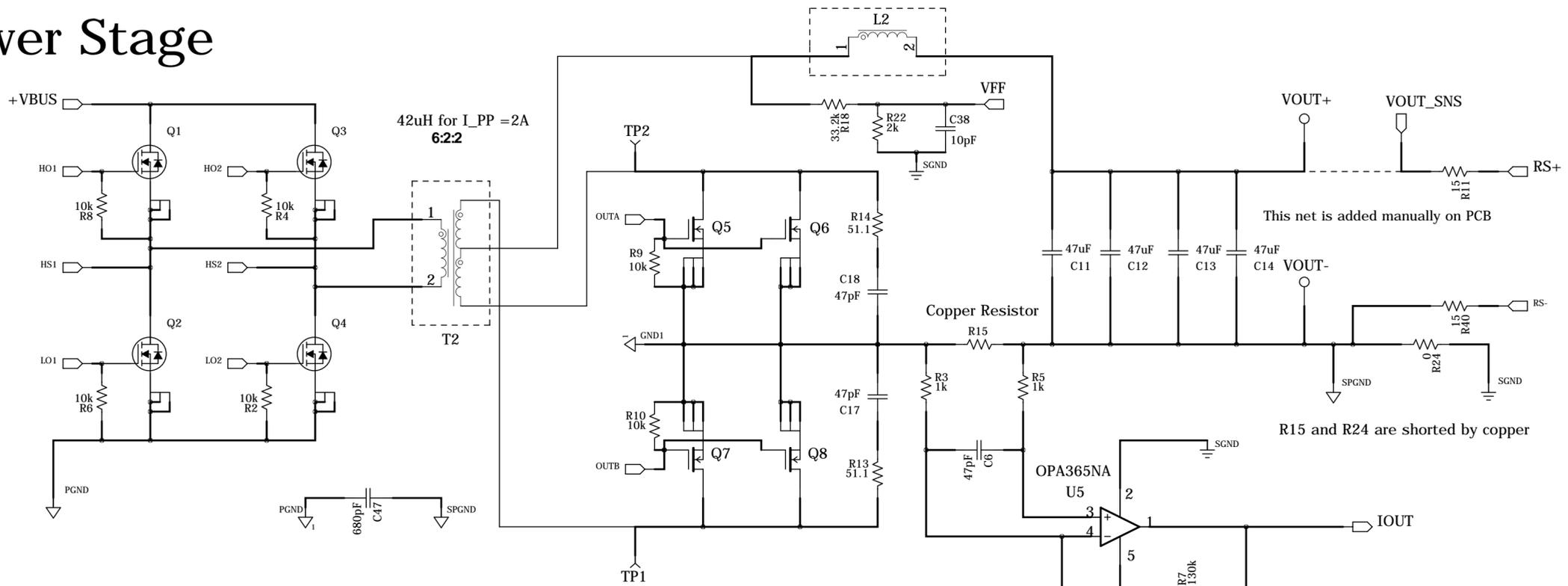


Power Stage



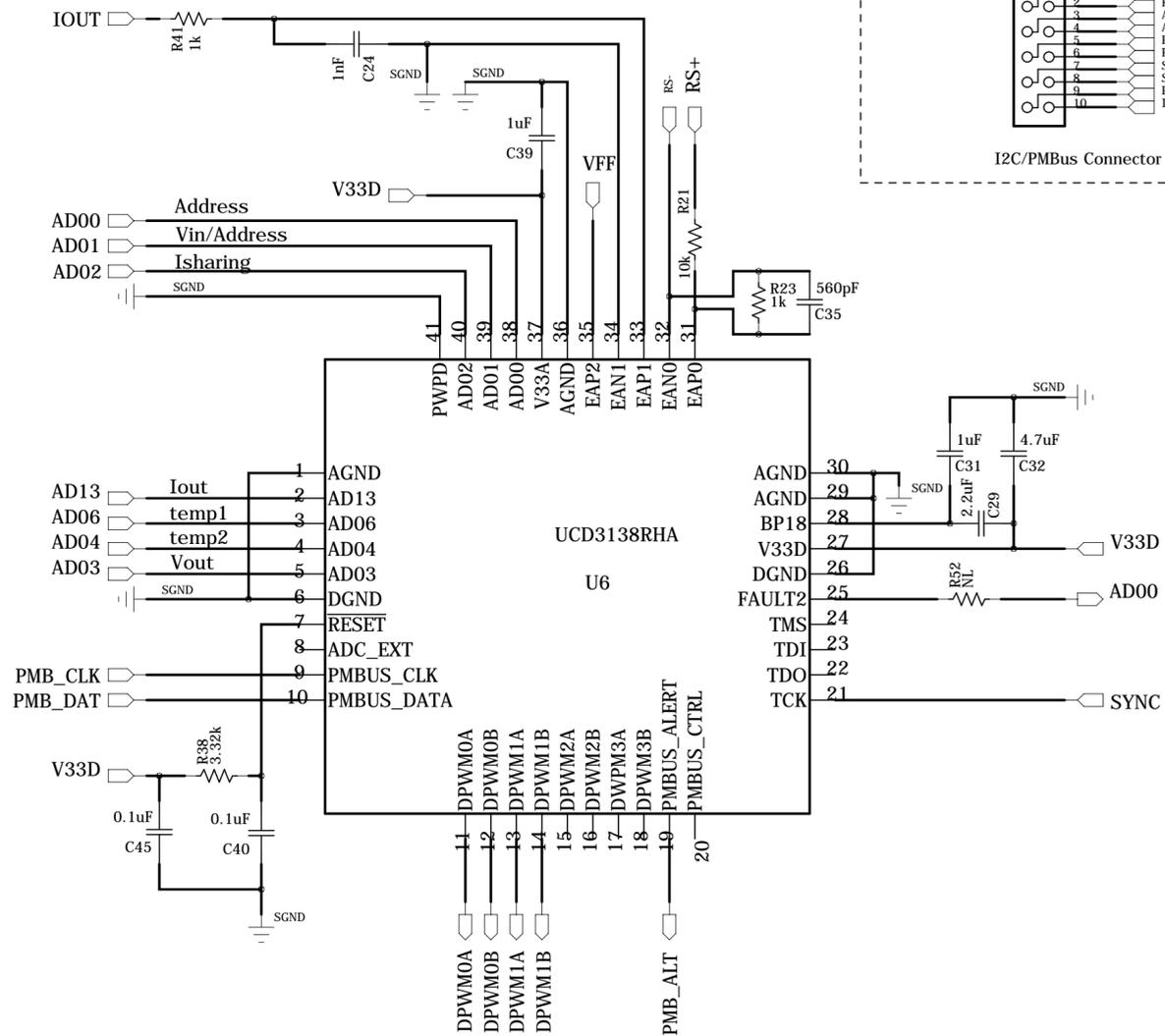
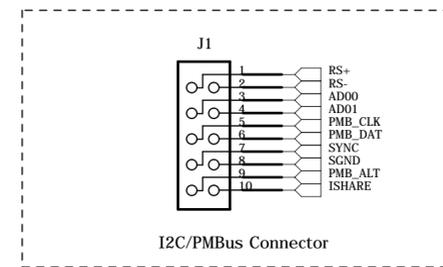
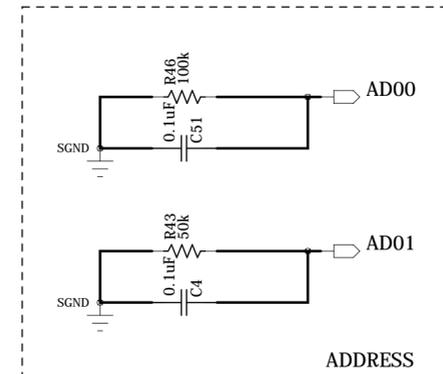
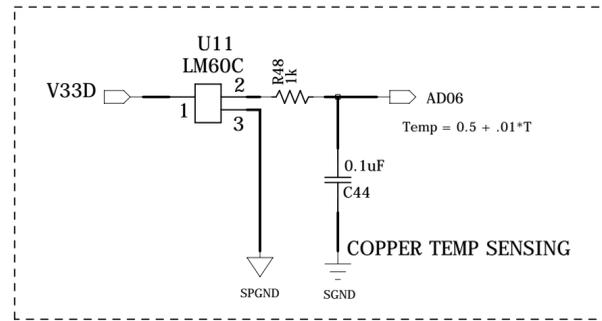
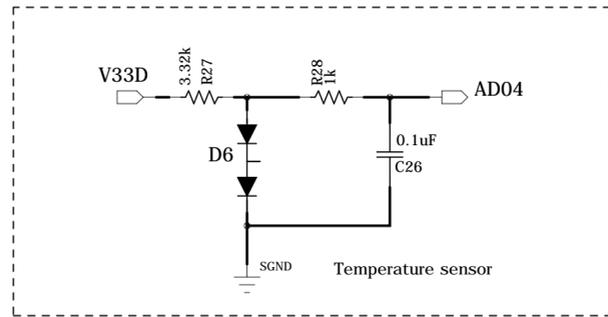
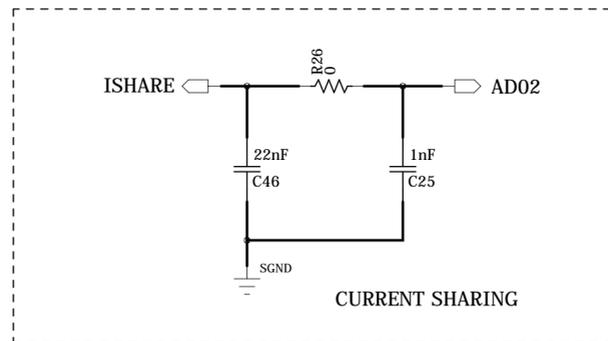
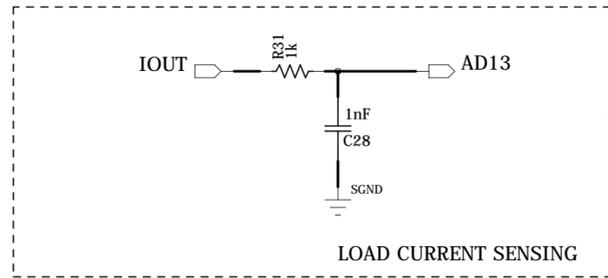
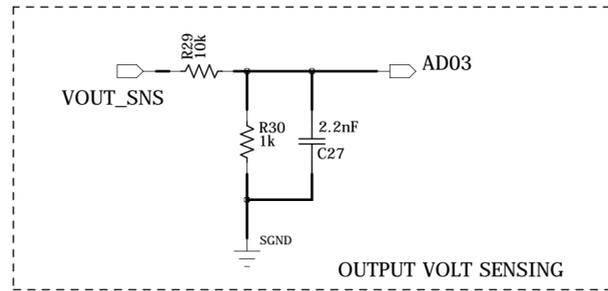
Texas Instruments

Title			UCD3138PWR153-HSFB 1/8 Brick		
Size	Number	PWR-153		Rev	A
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Date	4/23/2012	Drawn by	Fan Wang		
Filename	PWR-153-v3-10pin.sch	Sheet	1	of	3

Engineer Sean Xu

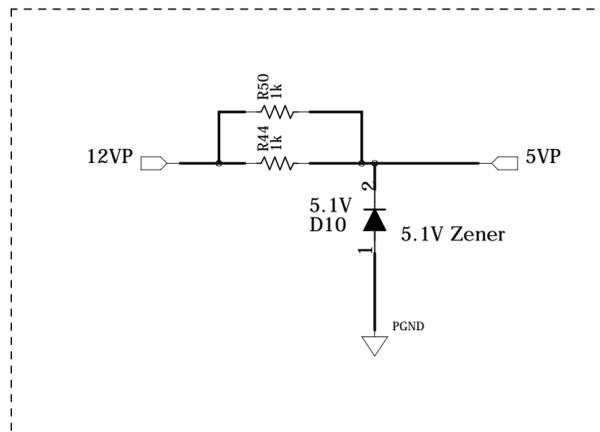
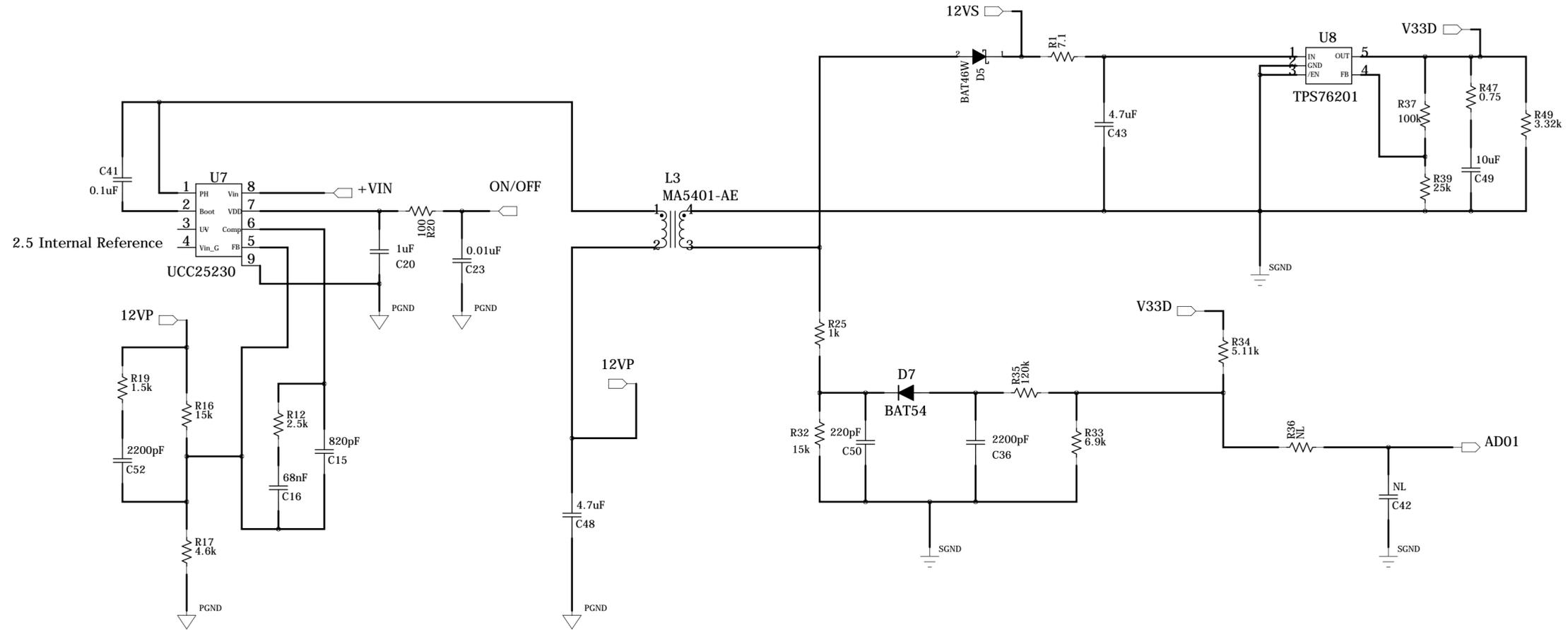
7/9/2012

Control Circuit



Size C	Number PWR-153	Texas Instruments	Rev A
Date 4/23/2012	Drawn by Fan Wang		
Engineer Sean Xu	Filename PWR-153-v3-10pin.sch	Sheet 2 of 3	

Bias Supply



Size C	Number Texas Instruments	Rev A
PWR-153		
Date 4/23/2012	Drawn by Fan Wang	
Engineer Sean Xu	Filename PWR-153-v3-10pin.sch	Sheet 3 of 3

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